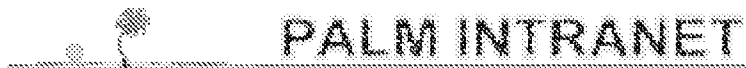


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Application#	Patent#	PG Pub#	Status	Date Filed	Title	Examiner Name
06863882	4720515		150	05/16/1986	EPOXY RESIN COMPOSITION FOR ENCAPSULATING SEMICONDUCTOR	NOT,DEFINED
08400769	5676318		150	03/08/1995	METHOD OF RECOVERING VALUABLE SUBSTANCES FROM PRINTED CIRCUIT BOARD	MORGAN,EILEE
08554159	5715592		150	11/06/1995	PARTS DISASSEMBLING APPARATUS	VO,PETER DUNC
08649486	5743936		150	05/17/1996	METHOD OF RECOVERING VALUABLES FROM PRINTED WIRING BOARD HAVING ELECTRONIC COMPONENTS MOUNTED THEREON	ANDREWS,MEL
08685665	5780536		150	07/24/1996	JOINING MEMBER AND METHOD FOR DISINTEGRATING JOINED STRUCTURE	CAIN,EDWARD
08883602	5801358		150	06/26/1997	METHOD FOR DISINTEGRATING JOINED STRUCTURE WITH HIGH FREQUENCY FIELDS	LEUNG,PHILIP

<u>08927197</u>	Not Issued		161	09/11/1997	FLAME RETARDENT RESIN COMPOSITION	WARZEL,MARK
<u>08954264</u>	<u>6001921</u>		150	10/20/1997	FLAME RETARDANT RESIN COMPOSITION	WARZEL,MARK
<u>09034234</u>	Not Issued		161	03/04/1998	APPARATUS FOR SEPARATING PARTS FROM A PRINTED WIRING BOARD AND SEPARATING METHOD THEREOF	TUGBANG,ANTI
<u>09184989</u>	<u>6242110</u>		150	11/03/1998	EPOXY RESIN COMPOSITION AND SEMICONDUCTOR DEVICE USING THE SAME	AYLWARD,DAV
<u>09185508</u>	<u>6284824</u>		150	11/04/1998	FLAME RETARDANT POLYCARBONATE RESIN COMPOSITIONS	TOOMER,CEPHI
<u>09195042</u>	<u>6156865</u>		150	11/19/1998	FLAME RETARDANT THERMOSETTING RESIN COMPOSITION	MICHL,PAUL
<u>09461197</u>	<u>6392003</u>		150	12/15/1999	PHENOL CONDENSATE FROM PHENOLS, AROMATIC COMPOUND AND N- CONTAINING HETEROCYCLIC	SELLERS,ROBEI
<u>09533775</u>	<u>6290919</u>		150	03/24/2000	Electrostatic separating apparatus	TRAN,THAO
<u>09555285</u>	<u>6433050</u>		150	07/24/2000	FLAME-RETARDANT POLYCARBONATE RESIN COMPOSITION	RAJGURU,UMAI
<u>09733998</u>	<u>6414091</u>	20010014723	150	12/12/2000	THERMOPLASTIC RESIN, PROCESS FOR PRODUCING SAME AND THEROPLASTIC RESIN COMPOSITION	PENG,KUO LIAN
<u>09816914</u>	Not Issued	20010039311	161	03/23/2001	Polysiloxane-containing copolymer and flame- retardant resin	PENG,KUO LIAN

					composition using the same	
09830016	7098276		150	04/20/2001	FLAME-RETARDANT EPOXY RESIN COMPOSITION AND SEMICONDUCTOR DEVICE MADE USING THE SAME	SELLERS,ROBEI
09958630	6602938		150	10/11/2001	FIRE-RESISTANT POLYCARBONATE RESIN COMPOSITION	BUTTNER,DAVI
10070827	6730402	20030152776	150	03/11/2002	FLAME-RETARDANT EPOXY RESIN COMPOSITION AND LAMINATE MADE WITH THE SAME	FEELY,MICHAEL
10077716	Not Issued	20020193552	161	02/19/2002	Flame retardant resin material and flame retardant resin composition	SELLERS,ROBEI
10518859	Not Issued	20060025560	71	12/17/2004	Biodegradable resin, biodegradable resin composition, biodegradable molded object, and process for producing biodegradable resin	LISTVOYB,GREG
10541747	7445835	20060147695	150	07/08/2005	KENAF-FIBER-REINFORCED RESIN COMPOSITION	TESKIN,FRED
10562736	Not Issued	20070060720	41	05/22/2006	Epoxy resin composition	FEELY,MICHAEL
10582675	Not Issued	20070148465	71	06/12/2006	Shape-memory resin performing remoldability and excellent in shape recovering property, and molded product composed of the cross-linked resin	TRUONG,DUC
10583463	Not Issued	20080071015	41	06/19/2006	Flame-Retardant Thermoplastic Resin Composition	OJURONGBE,OL
10590237	Not Issued	20080269361	83	08/22/2006	Flame-Retardant Resin Composition	LEE,DORIS

11477524	Not Issued	20060247393	41	06/30/2006	Composition of Biphenyl Epoxy Resin, Phenolbiphenylaralkyl Resin and Filler	SELLERS,ROBEI
11733689	Not Issued	20070251721	30	04/10/2007	INSULATION MATERIAL, WIRING BOARD, AND SEMICONDUCTOR DEVICE	SELLERS,ROBEI
12278644	Not Issued	20090137748	30	08/07/2008	POLYLACTIC ACID-MODIFIED POLYCARBODIIMIDE COMPOUND AND POLYLACTIC ACID RESIN COMPOSITION AND MOLDED ARTICLE COMPRISING THE SAME	TOSCANO,ALIC
12279525	Not Issued	20090054559	41	08/14/2008	POLYLACTIC ACID RESIN COMPOSITION AND MOLDED ARTICLE	USELDING,JOHN
12279529	Not Issued	20090069463	41	08/14/2008	POLYLACTIC ACID RESIN COMPOSITION AND MOLDED ITEM	USELDING,JOHN
12296227	Not Issued		19	01/01/0001	THERMALLY CONDUCTIVE RESIN MATERIAL AND MOLDED BODY THEREOF	,
12373785	Not Issued		19	01/01/0001	ALIPHATIC POLYESTER RESIN COMPOSITION AND METHOD FOR PRODUCTION THEREOF	,

Inventor Search Completed: No Records to Display.

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